

isoGLAS® EG Board - thermal insulation



Technical data

• Temperature resistance for a short period	650 °C 1000 °C
• Density	> 200 kg/m ³
• Average fiber diameter	10 µm
• Organic content	< 2%
• Shrinkage	< 1%
• Odour development	none
• Toxicity	none

In view of the variety of different installation and operation conditions and application and process engineering options, the information given in this prospectus can only provide approximate guidance.

Application areas

isoGLAS® EG Boards are insulation boards for use in high-temperature applications, in construction engineering fire protection, in heat engineering, in plant and furnace manufacturing, in process industry, in shipbuilding and aerospace applications and in car manufacturing. isoGLAS® EG is based on e-glass fibres and an inorganic bonding agent that does not release gas. This material combination makes isoGLAS® EG Boards an ideal insulation material.

Product characteristics

- Low heat conductivity
- Low weight
- Bonded fibres
- High dimensional stability and contour accuracy
- Dust-free
- No odour problems
- No pollutants
- Allows mechanical processing (drilling, milling, cutting, water jet cutting)

Product range

isoGLAS® EG - Board

The material is supplied in thicknesses between 5 and 25 mm. Further dimensions are possible on request.

isoGLAS® EG – 3D parts


Both individual parts and complete sub-assemblies can be designed and manufactured in accordance with your specifications.

Certifications



 **Quality management**
IATF 16949; ISO 9001

 **Environment management**
ISO 14001

 **Energy management**
ISO 50001



Application engineering questions?

We're here to help you at insulation@frenzelit.com